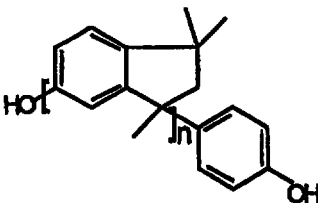




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(21) International Application Number: PCT/US99/03998 (22) International Filing Date: 24 February 1999 (24.02.99) (30) Priority Data: 09/031,286 26 February 1998 (26.02.98) US (71) Applicant: ALLIEDSIGNAL INC. [US/US]; 101 Columbia Road, P.O. Box 2245, Morristown, NJ 07962-2245 (US). (72) Inventors: McCARTHY, Thomas; 169 Dafrack Drive, Lake Hiawatha, NJ 07034 (US). SCHWIND, David; 12 Slabtown Creek Road, Blairstown, NJ 07825 (US). SMITH, Gordon; 1432 South Highland Avenue, Arlington Heights, IL 60005 (US). (74) Agents: CRISS, Roger, H. et al.; AlliedSignal Inc., Law Dept. (R. Fels), 101 Columbia Road, P.O. Box 2245, Morristown, NJ 07962-2245 (US).		(81) Designated States: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GE, GH, GM, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, UZ, VN, YU, ZW, ARIPO patent (GH, GM, KE, LS, MW, SD, SZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG). Published <i>With international search report.</i>
(54) Title: PREPARATION OF POLYINDANEBISPHENOLS AND POLYMERS DERIVED THEREFROM  (I) (57) Abstract Novel polyindanebisphenols or PIBPs for the preparation of new and improved thermosetting polymers having general formula (I) are provided. Also disclosed are thermoplastic or thermoset compositions prepared using the novel compounds of the invention, as well as methods of making and using the same. When copolymerized or reactive with other commercial resins such as, e.g., epoxy compounds, PIBP based polymers are characterized by high glass transition temperature ("Tg"), low dielectric constant, low moisture absorption, low coefficient of expansion, low cost, and can be processed on equipment typically used for the production of epoxy based laminates.		